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## Transient CHI Plasma Start-up and Non-inductive Current Ramp-up Simulations for NSTX-U

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## NSTX-U Research will Advance the ST as a Candidate for a Fusion Nuclear Science Facility (FNSF)



#### New large center stack in NSTX-U enables

- $B_T$ : Increases from 0.55 to 1 T
- Plasma current: 1 to 2 MA
- Discharge pulse duration: 1s to 5 s

### Second tangential Neutral Beam in NSTX-U enables

First NBI

Higher current drive at low plasma current



## **NSTX-U** Aims to Develop and understand non-inductive start-up/ramp-up to project to ST-FNSF operation

- Establish physics basis for ST-FNSF, and non-inductive start-up is essential in ST
  - Simplify the tokamak concept 1000kA to reduce cost and allow Aspect ratio optimization
- NSTX-U is striving for fully non-inductive operations
  - Transient Coaxial Helicity Injection (CHI) start-up is the front end of that objective
  - Plasma guns and EBW will be tested after those systems are technically ready



Current

# CHI is planned to be used as initial current seed for subsequent non-inductive current ramp-up in NSTX-U

#### CHI in NSTX/NSTX-U





#### **NIMROD Simulation**



F. Ebrahimi (Invited Talk) PI2.00002 2:30-3:00PM Wednesday, PoP (2013) E.B. Hooper, NP8.00023 Wednesday AM, PoP (2013)

## Plasma Discharge Ramping to 1MA Required 35% Less Inductive Flux when Coaxial Helicity Injection (CHI) is Used



27 kJ of stored capacitor bank energy used for CHI plasma start-up

CHI produced plasma is clean (Discharges have transitioned to H-mode after coupling to induction)

28 GHz Cut-off density at 1T ~1e13 cm<sup>-3</sup> ( >2 x CHI plasma density)

## CHI start-up to ~0.4MA is projected for NSTX-U, and projects to ~20% start-up current in next-step STs



Injector flux in NSTX-U is ~ 2.5 times higher than in NSTX  $\rightarrow$  supports increased CHI current

Parameters	NSTX	NSTX- U	ST- FNSF
Toroidal flux [Wb]	2.5	3.9	15.8
Sustained $I_p$ [MA]	1	2	10
Injector flux (Wb)	0.047	0.1*	0.66
Projected Start-up current (MA)	0.2	0.4	2.0

\*Theoretical Maximum in NSTX-U > 0.3 Wb

#### **Projection based on:**

- Injector flux scales with device size
- Toroidal flux in device
- Injector flux footprint width scaled proportional to minor radius

J.E Menard, et al., NF (2012)

*NSTX-U* R. Raman, et al., PoP (2011)

### Bridge Electron Temperature Gap Between CHI Start-up and Current Ramp-up Requirements with ECH Heating



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55<sup>th</sup> APS DPP (Raman)

### Non-inductive Ramp-up from ~0.4MA to ~1MA Projected to be Possible with Tangential NBI

- Compared to First NBI, the Second Tangential NBI provides 3-4x higher CD at low I<sub>P</sub>:
  - 1.5-2x higher current drive efficiency, plus
  - − 2x higher absorption (40 $\rightarrow$ 80%) at low I<sub>P</sub> = 0.4MA
- TSC simulation of non-inductive ramp-up from initial CHI target
  - Simulations being improved to use TRANSP/NUBEAM loop within TSC



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J.E Menard, et al., NF (2012)

R. Raman, et al., NF (2013) Nov 11-15, 2013

## NSTX-U Aims to Develop Full Non-inductive Start-up and Current Ramp-up in support of FNSF and next step Tokamaks

- 0.2MA closed flux current generation in NSTX validates capability of CHI for high current generation in a ST
- Successful coupling of CHI started discharges to inductive ramp-up & transitioning to an H-mode demonstrates compatibility with highperformance plasma operation
- Favorable scaling with increasing machine size (from two machines of vastly different size, HIT-II and NSTX and in TSC simulations)
- NSTX-U is well equipped with new capabilities to study full non-inductive start-up and current ramp-up
  - 2x Higher TF, 1MW ECH, Second Tangential NBI for CD, 2x higher CHI voltage, >2.5x more injector flux

## **Back-up Slides**



### **Back-up Slides**







**NSTX-U** 

- Insulator Resistance > 1 Ohm
- Resistance to be maintained only during the plasma start-up phase (<30 ms in duration)</li>
- The actual high-voltage phase < plasma start-up phase
- During the plasma start-up phase, there is no pre-existing plasma that can short out the insulator (and CHI current path is controlled by pre-programmed vacuum field line pattern)
- After the high-voltage phase, insulator could be shorted-out, if necessary

# Because the Required Insulator Resistance is very low (few times the plasma impedance) other possibilities exist

- Layers of thin resistive metal coated with insulating layers
- Powdered, weakly bonded, insulator sandwiched between two metal plates
- The HIT-Si device used an insulator spray to achieve insulation *in a plasma environment* in an more complicated vessel geometry
- .... Other possibilities (including conventional insulator technology currently planned for next step machines to insulate PF coils and other components)
- Insulator could be hidden behind metallic structure as on NSTX-U

## **Assumptions for HIT-II / NSTX / FNSF / ST Pilot Plant**

- Normalized internal inductance = 0.35
- The gap 'd' is assumed to scale as the minor radius d = 0.9 \* a
- The injector flux scales as R\*Ip
- Injector current = 1.2 or 1.3 times the bubble burst current
- Plasma poloidal flux = 80% of Injector flux
- The current multiplication factor Ip/Iinj is held below the limiting value of M = Toroidal flux / Injector flux
- Injector area = 2.pi.R\*d/4

# Modeling shows that the ramp-up strategy significantly benefits from 1-2 MW ECH to heat CHI plasma •GENRAY

- In a 500kA decaying inductive discharge, TSC simulations indicate 0.6MW of absorbed ECH power could increase  $T_e$  to ~400eV in 20ms (with 50% ITER L-mode scaling)
  - ECH absorption and deposition profile being modeled using GENRAY
  - CHI discharge densities at  $T_e = 70 \text{ eV}$  would allow 60% first-pass absorption by 28 GHz ECH in NSTX-U
- Increased T<sub>e</sub> predicted to significantly reduce I<sub>p</sub> decay rate
  - ECH heated plasma can be further heated with HHFW
  - Maximum HHFW power < 4MW, higher  $B_T$  in NSTX-U would improve coupling
  - HHFW has demonstrated heating a 300 kA / 300 eV plasma to > 1 keV in 40ms





# CHI is planned to be used as initial current seed for subsequent non-inductive current ramp-up in NSTX-U

#### CHI in NSTX/NSTX-U Absorber Coils 1 MW ECH TF Inner *Insulating* TF **Outer TF** gaps OH HHFW Coil Antenna J<sub>pol</sub> X B<sub>tor</sub> l<sub>ini</sub> Capacitor Injector Bank up to 50 mF Lower Divertor Coils



## TSC (axisymmetric 2D) simulation of CHI startup



- > 2.5 x Injector Flux (Ip proportional to flux )
- TF = 1 T (increases current multiplication)
- ECH (increases T<sub>e</sub>)
- > 2kV CHI voltage (increases flux injection)
- Full Li coverage (reduces low-Z imp.)
- Metal divertor, Cryo pump (increases  $T_e$ )

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## Start-up and Ramp-up Research Involves Three Parallel Paths that Will be Linked as Technical Capabilities Permit

# (a) Generate and increase current produced by CHI

- Heat with ECH (to 200-400eV)
- Then heat with HHFW (to > 1keV)
- Then ramp-up current using NBI and BS current overdrive
- (b) Current ramp-up of intermediate I<sub>p</sub> plasmas (Wave particle TSG)
  - Progressively increase initial current (from 0.3 to 0.5MA) and ramp-up using HHFW and BS current overdrive
  - Assist extension of NBI CD to lower  ${\rm I}_{\rm p}$



# (c) Current ramp-up at near full $I_p$ with NBI and bootstrap current overdrive

 Progressively reduce initial current from 0.9 to 0.4MA and non-inductively rampup current to 1MA using NBI and BS current overdrive

## Externally Produced Toroidal Field makes CHI much more Efficient



$$I_P = I_{inj} (\psi_T / \psi_{inj})$$

- Current multiplication increases with toroidal field
  - Favorable scaling with machine size
  - Increases efficiency (10 Amps/Joule in NSTX)
  - Smaller injector current to minimize electrode interaction





## **NSTX CHI Research Follows Concept Developed in HIT-II**



#### **Concept exploration device HIT-II**

- Built for developing CHI
- Many close fitting fast acting PF coils
- 4kV CHI capacitor bank

## NSTX plasma is ~30 x plasma volume of HIT-II



#### **Proof-of-Principle NSTX device**

- Built with conventional tokamak components
- Few PF coils
- 1.7kV CHI capacitor bank

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## Very High Current Multiplication (Over 70 in NSTX) Aided by Higher Toroidal Flux



#### -30kA of injector current generates 120kA of plasma current

-Best current multiplication factor is 6-7

## -Current multiplication factor in NSTX is 10 times greater than that in HIT-II



## - Over 200kA of current persists after CHI is turned off

R. Raman, B.A. Nelson, D. Mueller, et al., PRL 97, (2006) 17002



## Simulations Using TSC, coupled to TRANSP/NUBEAM and GENRAY being used for Current Ramp-up Simulations

## CHI Research on NSTX-U Benefits from numerous hardware upgrades

- > 2.5 x Injector Flux (proportional to I<sub>p</sub>)
- TF = 1 T (increases current multiplication)
- ECH (increases  $T_e$ )
- > 2kV CHI voltage (increases flux injection)
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